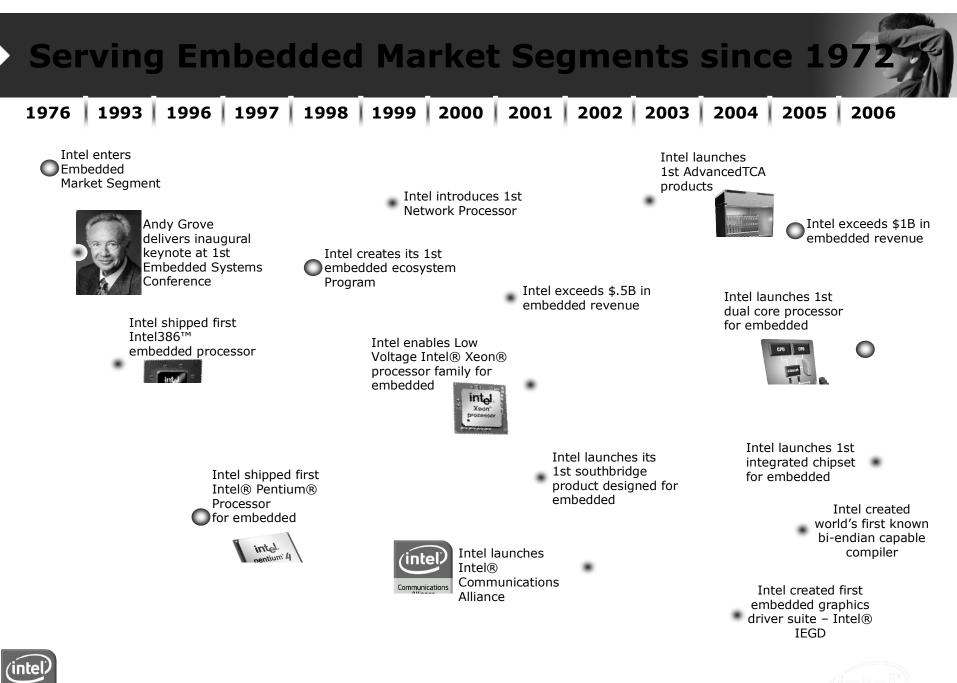


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Communications

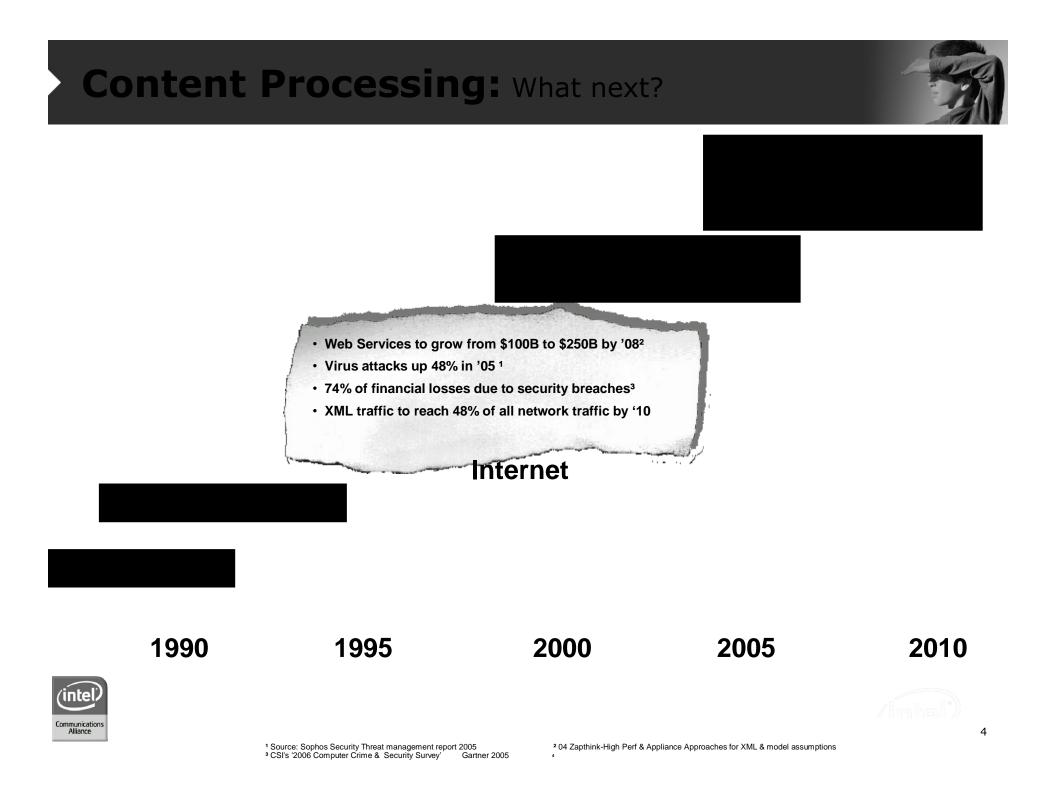
## **Market Segment demands**

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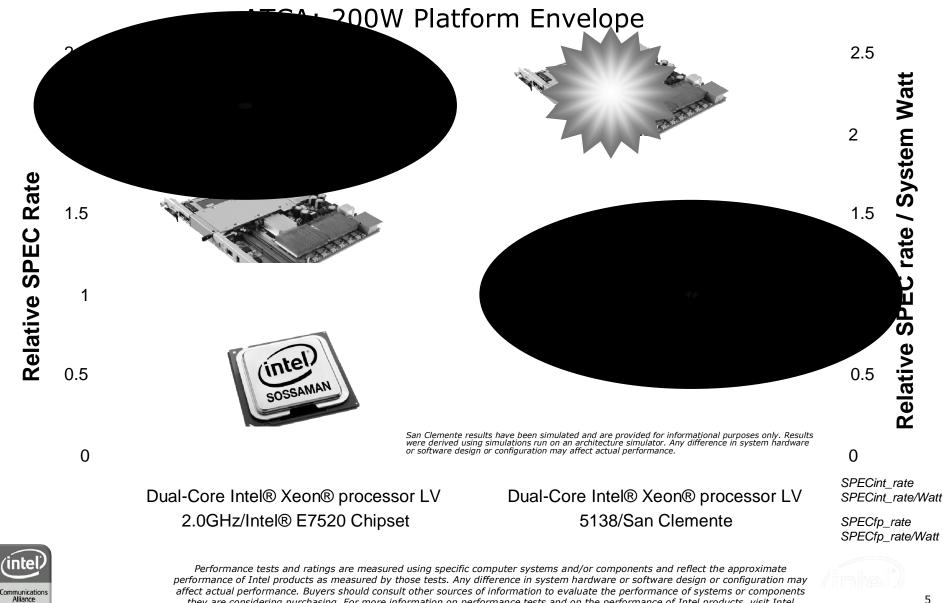
> Datacenter power and cooling limitations Harsh environment







## Thermal Density: Can AdvancedTCA® Meet Performance Demands?



they are considering purchasing. For more information on performance tests and on the performance of Intel products, visit Intel Performance Benchmark Limitations (http://www.intel.com/performance/resources/limits.htm).

### **Modularity Evolution** Standards Investment Lead customer adoption **Deployments Scaling Rapid Growth Platform definition Ecosystem evolution** NEC Huawei Technologies JTStarcom SERVICE AVAILABILITY ALCATEL Messaging FORUM SIEMENS PICMG FUJITSU NØRTEL Entertainment Siemens RNCi **Open Modular** FUITSU COMPUTERS **Computing Specifications** Nortel's VSE Platform SIEMENS Communications Alliance Advanced TCA® SCOPE What's Your **Modularity in Modular Works** Modular Strategy? the Network 2006 - '07 2000 - '03 2004 - '05

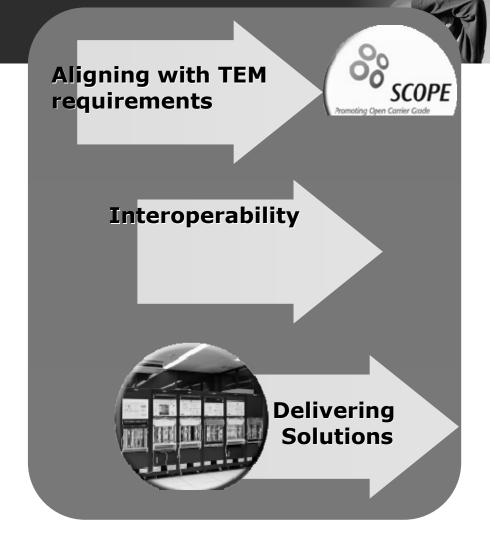


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## **Barriers to Growth**

- Multidimensional Open Industry Standards support "all" applications
  - Only a subset may be needed for a specific application
- Too many optional requirements and options
  - Confusion and fragmentation
- Inconsistent interpretations of mandatory requirements
  - No objective, consistent criteria for conformance or certification
- Limited overall system view
  - Low confidence in Platform Interoperability





SCOPE\* + CP-TA\* + MCP Solutions Labs REMOVING THE BARRIERS

## Summary



AdvancedTCA® broadly accepted by communications market segment

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AdvancedTCA® meets these processing demands for rugged environments

Intel and other category leaders continue to invest in Advanced ICA®

(At maybe) "mainstream" (At maybe)



For more information visit: <u>www.intel.com/go/atca</u>

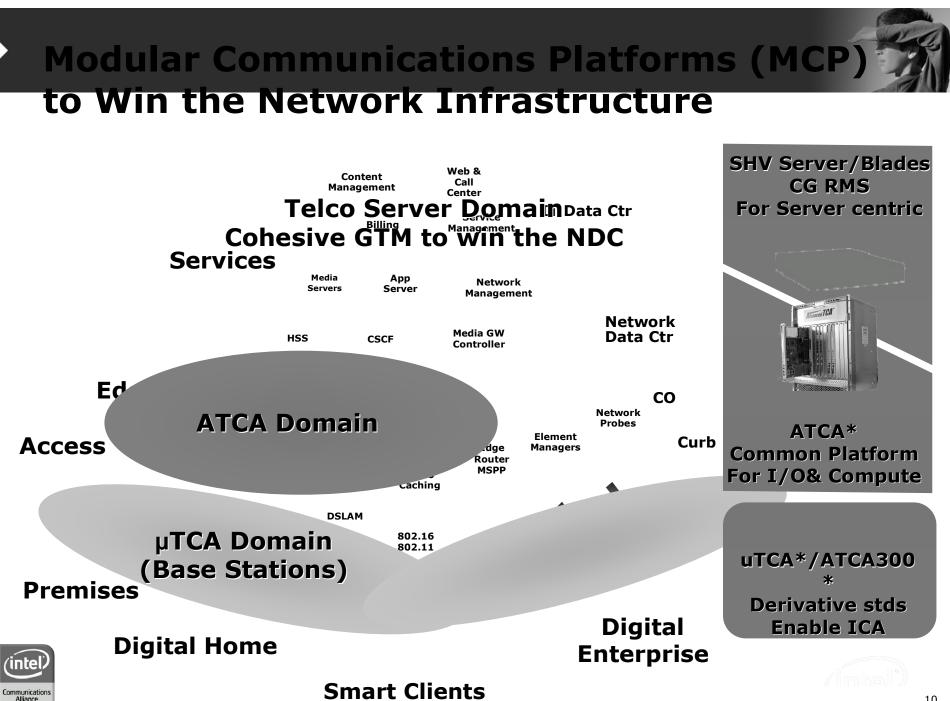




## Backup





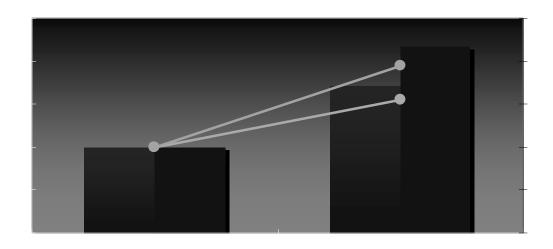


## Increasing Performance Density in AdvancedTCA\* SBC (Thermal Density: Foil 12)



Excellent system performance/watt progression from Dual Core Intel® Xeon® Processor LV 2.0GHz (Sossaman) with Intel® E7520 chipset (Lindenhurst)

San Clemente delivers performance similar to Intel® 5000V and 5000P, with better system performance/watt



San Clemente results have been simulated and are provided for informational purposes only. Results were derived using simulations run on an architecture simulator. Any difference in system hardware or software design or configuration may affect actual performance.

SPECint\_rate SPECint\_rate/Watt

SPECfp\_rate SPECfp\_rate/Watt

## Crown King increase integer performance by ~70% and Perf/watt by 54%



Performance tests and ratings are measured using specific computer systems and/or components and reflect the approximate performance of Intel products as measured by those tests. Any difference in system hardware or software design or configuration may affect actual performance. Buyers should consult other sources of information to evaluate the performance of systems or components they are considering purchasing. For more information on performance tests and on the performance of Intel products, visit <u>Intel</u> <u>Performance Benchmark Limitations</u> (http://www.intel.com/performance/resources/limits.htm). Meeting Market Segment Needs

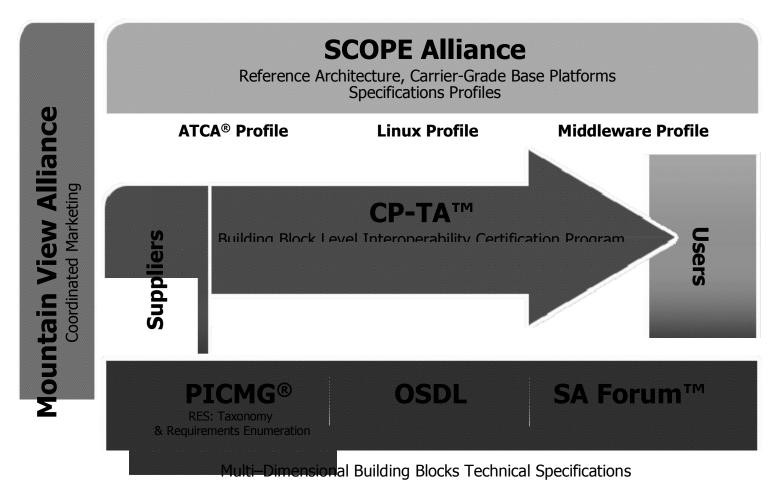


# Multicore Integration Thermal Density Content Processing





## **Industry Landscape**





Source: Communications Platforms Trade Association (CP-TA)

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## Accelerating a Standards-based 12 Network

## Fourth Generation of ATCA\* Building Blocks

## Processor Performance and Efficiency



